

ABSTRACT

A CMP apparatus is provided for polishing wafers that are substrates to be polished by CMP. The CMP apparatus comprises a stage that is structured to be rotatable and holds a wafer to be polished, a polishing head holding section that holds a polishing head equipped with a polishing pad over the stage, a polishing head storage section that stores replacement polishing heads equipped with polishing pads; and a polishing head replacement mechanism that replaces the polishing head held by the polishing head holding section with the replacement polishing heads stored in the polishing head storage section.